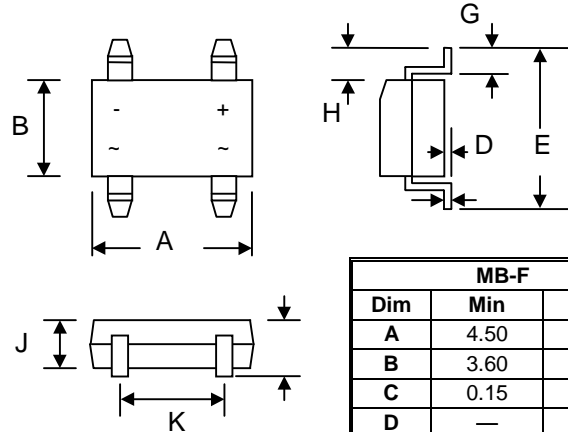


Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage Application
- Plastic Case Material has UL Flammability Classification Rating 94V-O



MB-F		
Dim	Min	Max
A	4.50	4.95
B	3.60	4.10
C	0.15	0.35
D	—	0.20
E	6.40	7.00
G	0.50	1.10
H	1.30	1.70
J	1.20	1.60
K	2.30	2.70
L	—	1.80
All Dimensions in mm		

Mechanical Data

- Case: MB-F, Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Weight: 0.134 grams (approx.)
- Mounting Position: Any
- Marking: Type Number
- **Lead Free: For RoHS / Lead Free Version**

Maximum Ratings and Electrical Characteristics @ $T_A=25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	KMB 22F	KMB 23F	KMB 24F	KMB 25F	KMB 26F	KMB 28F	KMB 210F	KMB 215F	KMB 220F	KMB 225F	Unit	
Peak Repetitive Reverse Voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	250	V	
Working Peak Reverse Voltage	V_{RWM}												
DC Blocking Voltage	V_R												
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	56	70	105	140	175	V	
Average Rectified Output Current @ $T_L = 90^\circ\text{C}$	I_O	2.0										A	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	50										A	
Forward Voltage @ $I_F = 2.0\text{A}$	V_{FM}	0.50			0.70		0.85		0.95		0.92	V	
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	I_{RM}	0.1						20					mA
Typical Thermal Resistance (Note 1)	$R_{\theta JL}$ $R_{\theta JA}$	10						50					$^\circ\text{C/W}$
Typical Junction Capacitance	C_j	110					30		110				pF
Operating Temperature Range	T_j	-65 to +150										$^\circ\text{C}$	
Storage Temperature Range	T_{STG}	-65 to +150										$^\circ\text{C}$	

Note: 1. Mounted on P.C. Board with 5.0mm² copper pad area.